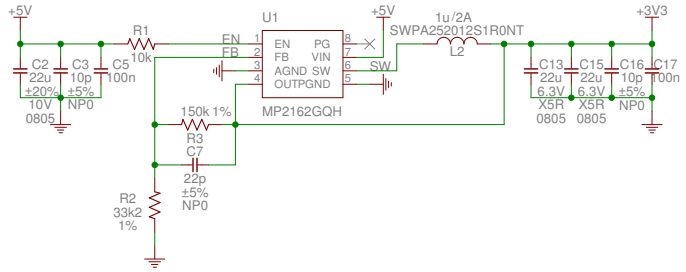
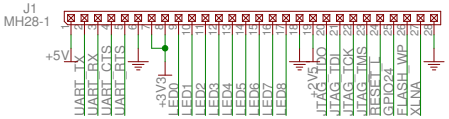
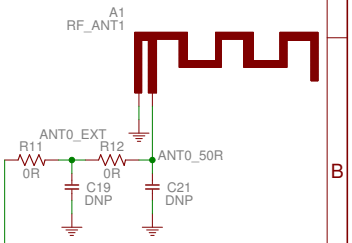
Power Supply



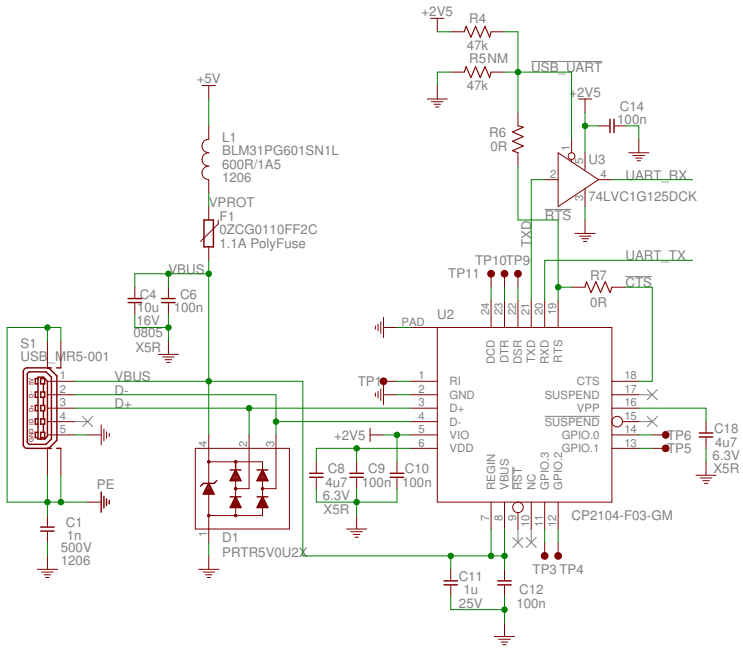
North Connector



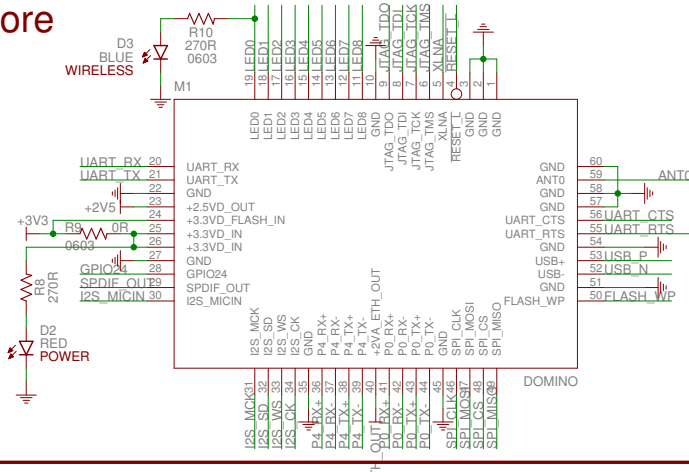
Antenna



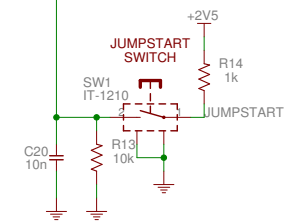
USB ⇔ UART Bridge



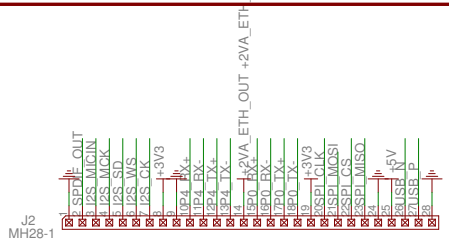
Core



Jumpstart



South Connector



Resistors are 5% 1/16W 0402 unless otherwise specified
Ceramic capacitors are ±10% 50V X7R dielectric 0402 unless otherwise specified

DOMINO Pi
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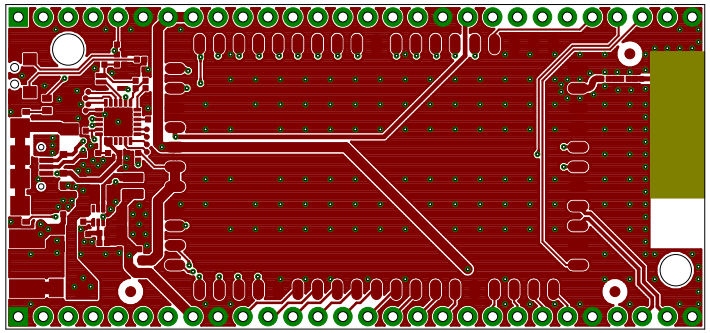
Domino Pi	
30/12/14 20:08	
Sheet: 1/1	Rev.C



DRILL CHART: TOP TO BOTTOM

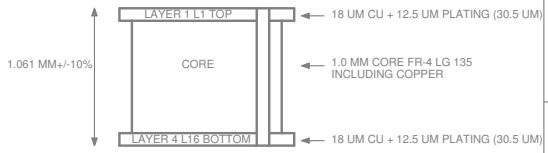
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	269	YES
×	2	22	0.55	2	NOT
◰	3	31	0.80	2	NOT
◇	4	40	1.02	56	YES
⧖	5	126	3.20	2	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	26 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	14.5 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	10 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



NOTES:

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3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE WHITE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY.
EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING BLACK INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE.
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   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

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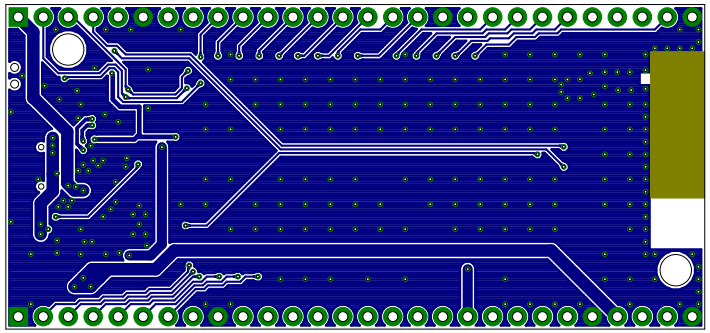
Component Side (.CMP) | Rev. C



DRILL CHART: TOP TO BOTTOM

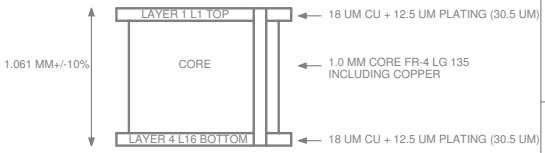
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	269	YES
×	2	22	0.55	2	NOT
◰	3	31	0.80	2	NOT
◇	4	40	1.02	56	YES
⧖	5	126	3.20	2	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	26 mils		N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	14.5 mils		6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	10 mils		6 mils	6 mils

STACK-UP FOR REFERENCE



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3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
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5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE WHITE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY.
EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING BLACK INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE.
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
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   * 1 MM BOARD THICKNESS
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

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30/12/14 20:10

Solder side (.SOL) | Rev. C

DRILL CHART: TOP TO BOTTOM

LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
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◰	3	31	0.80	2	NOT
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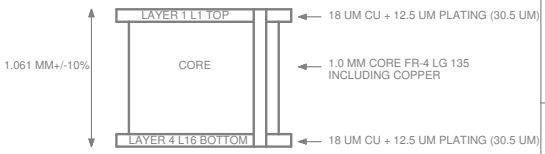
TOP, BOTTOM	90 Ohms	14.5 mils		6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	10 mils		6 mils	6 mils

STACK-UP FOR REFERENCE



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Silk screen CMP (.PLC) | Rev. C

DRILL CHART: TOP TO BOTTOM

LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	269	YES
×	2	22	0.55	2	NOT
◳	3	31	0.80	2	NOT
◈	4	40	1.02	56	YES
⧖	5	126	3.20	2	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

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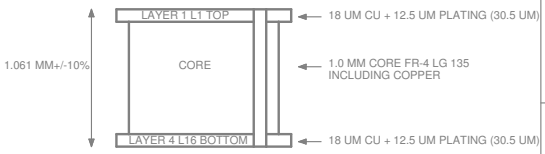
TOP, BOTTOM	90 Ohms	14.5 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	10 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



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Silk screen SOL (.PLS) | Rev. C

DRILL CHART: TOP TO BOTTOM

LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	269	YES
×	2	22	0.55	2	NOT
◰	3	31	0.80	2	NOT
◈	4	40	1.02	56	YES
⧖	5	126	3.20	2	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

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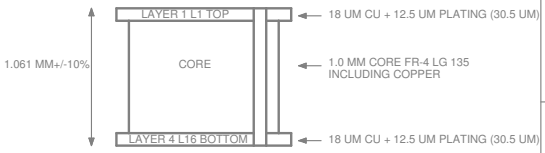
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	14.5 mils		6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	10 mils		6 mils	6 mils

STACK-UP FOR REFERENCE



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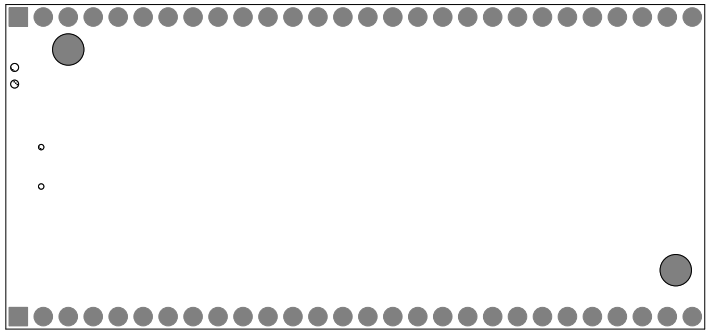
Solder stop mask CMP (.STC) | Rev. C



DRILL CHART: TOP TO BOTTOM

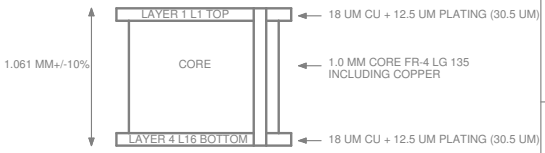
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	269	YES
×	2	22	0.55	2	NOT
◰	3	31	0.80	2	NOT
◇	4	40	1.02	56	YES
⧖	5	126	3.20	2	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	26 mils		N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	14.5 mils		6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	10 mils		6 mils	6 mils

STACK-UP FOR REFERENCE



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6. BOARD TO HAVE WHITE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY.
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Domino Pi

30/12/14 20:10

Solder stop mask SOL (.STS) | Rev. C

DRILL CHART: TOP TO BOTTOM

LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	269	YES
×	2	22	0.55	2	NOT
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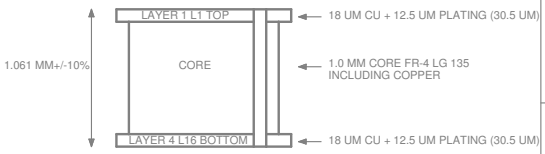

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Domino Pi

30/12/14 20:10

Cream frame CMP (.CRC) | Rev. C

DRILL CHART: TOP TO BOTTOM

LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	269	YES
×	2	22	0.55	2	NOT
◰	3	31	0.80	2	NOT
◈	4	40	1.02	56	YES
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Layer	Impedance	Trace Width		Trace Separation	Ground Separation
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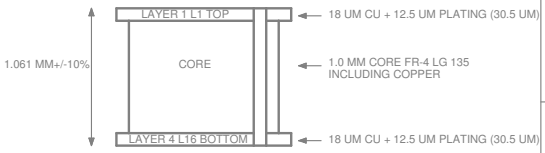
STACK-UP FOR REFERENCE



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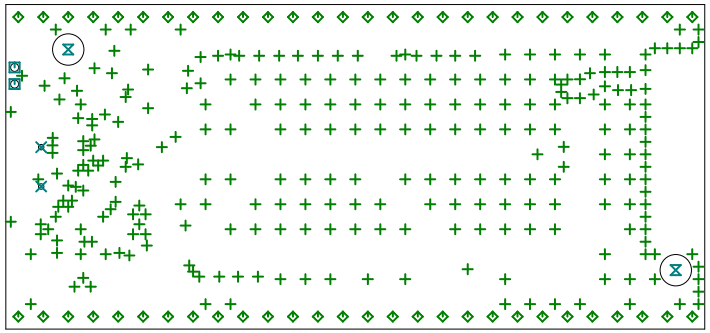
DOMINO Pi
WIFI 4 THINGS

Domino Pi

30/12/14 20:10

Cream frame SOL (.CRS) | Rev. C



DRILL CHART: TOP TO BOTTOM

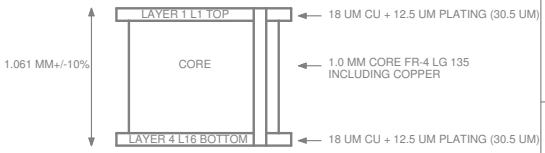
LAYER-STACK
01-16
01-20

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	269	YES
×	2	22	0.55	2	NOT
◰	3	31	0.80	2	NOT
◇	4	40	1.02	56	YES
⧖	5	126	3.20	2	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	26 mils		N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	14.5 mils		6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B		
Layer	Impedance	Trace Width		Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	10 mils		6 mils	6 mils

STACK-UP FOR REFERENCE



NOTES:

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30/12/14 20:10

Drill data (.DRD) | Rev. C

DRILL CHART: TOP TO BOTTOM

LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	269	YES
×	2	22	0.55	2	NOT
◰	3	31	0.80	2	NOT
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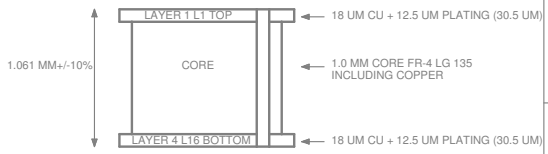

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CC-BY-SA

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Component Assembly CMP (.ASC) | Rev. C

DRILL CHART: TOP TO BOTTOM

LAYER-STACK

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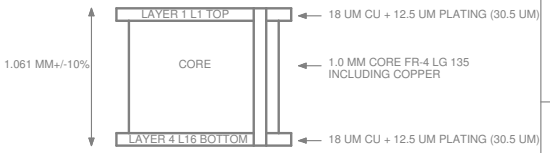

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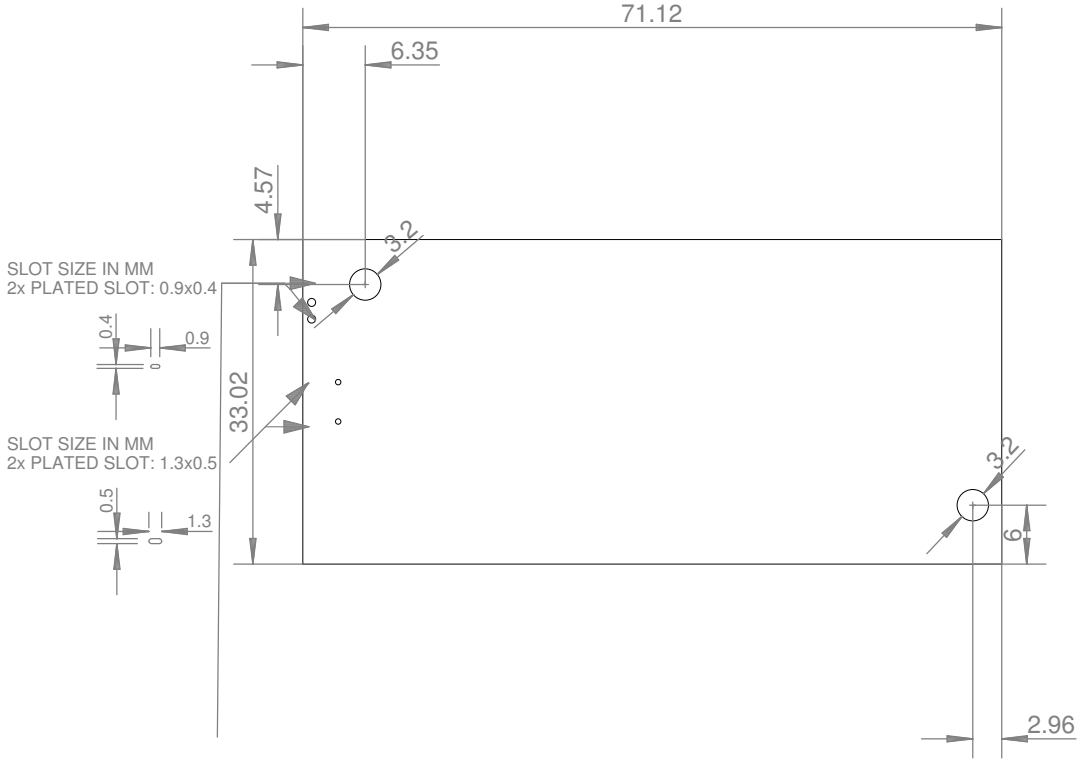
Domino Pi

30/12/14 20:10

Component Assembly SOL (.ASS) | Rev. C



DRILL CHART: TOP TO BOTTOM

LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
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×	2	22	0.55	2	NOT
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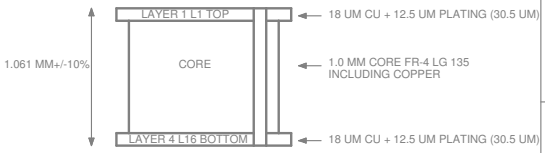

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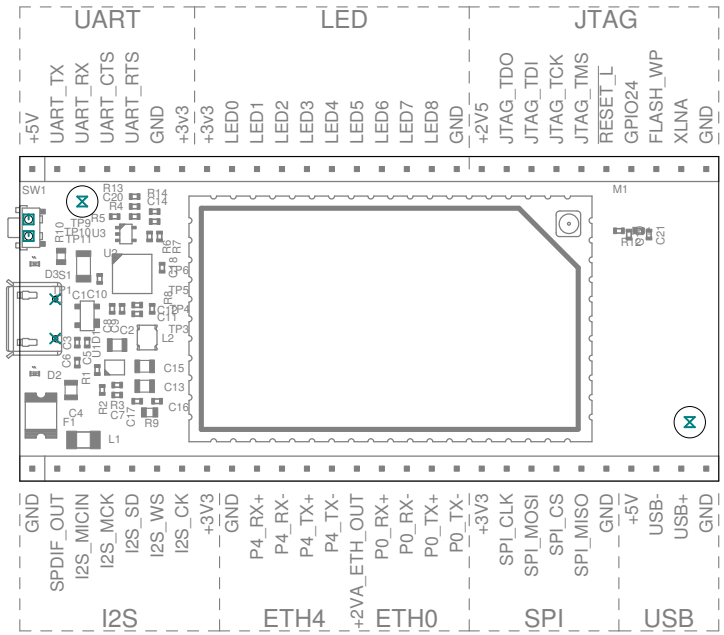
DOMINO Pi
WIFI 4 THINGS

Domino Pi

30/12/14 20:10

Outline (.OLN) | Rev. C



DRILL CHART: TOP TO BOTTOM

LAYER-STACK

01-20

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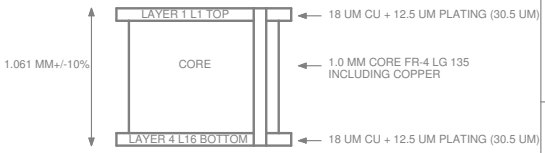

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DOMINO Pi
WIFI 4 THINGS

Domino Pi

30/12/14 20:10

Pinout (.PIN) | Rev. C

Domino Pi Rev. C

Item	Qty	Value	Manufacturer	Device	Package	Reference	Description	Remarks
1	1	1n	ANY	C1206_1n_X7R_10%_CER_500V	C1206	C1	CAP CER 1000PF 500V 10% X7R 1206	
2	1	1u	ANY	C0402_1u_X7R_10%_CER_25V	C0402	C11	CAP CER 1UF 25V 10% X7R 0402	
3	2	22u	ANY	C0805_22u_X5R_20%_CER_6V3	C0805	C13, C15	CAP CER 22UF 6.3V 20% X5R 0805	
4	0	DNP	NONE	C0402_DNP	C0402	C19(DNP), C21(DNP)	CAP DNP 0402	
5	1	22u	ANY	C1206_22u_X7R_20%_CER_10V	C0805	C2	CAP CER 22UF 10V 20% X7R 1206	
6	1	10n	ANY	C0402_10n_X7R_10%_CER_50V	C0402	C20	CAP CER 10000PF 50V 10% X7R 0402	
7	2	10p	ANY	C0402_10p_NP0_5%_CER_50V	C0402	C3, C16	CAP CER 10PF 50V 5% NP0 0402	
8	1	10u	ANY	C0805_10u_X5R_10%_CER_16V	C0805	C4	CAP CER 10UF 16V 10% X5R 0805	
9	7	100n	ANY	C0402_100n_X7R_10%_CER_50V	C0402	C5, C6, C9, C10, C12, C14, C17	CAP CER 0.1UF 50V 10% X7R 0402	
10	1	22p	ANY	C0402_22p_NP0_5%_CER_50V	C0402	C7	CAP CER 22PF 50V 5% NP0 0402	
11	2	4u7	ANY	C0402_4u7_X5R_10%_CER_6V3	C0402	C8, C18	CAP CER 4.7UF 6.3V 10% X5R 0402	
12	1	PRTR5V0U2X	NXP	PRTR5V0U2X	SOT143B	D1	TVS DIODE ARRAY 2CH 5V SOT143	
13	1	RED	ANY	LED0603-RED	LED0603	D2	LED RED CLEAR 0603 SMD	
14	1	BLUE	ANY	LED0603-BLUE	LED0603	D3	LED BLUE CLEAR 0603 SMD	
15	1	0ZCG0110FF2C	BEL FUSE INC	0ZCG0110FF2C	PTC1812	F1	PTC RESETTBLE 1.10A 8V CHIP 1812	
16	2	MH28-1	ANY	MH28-1-0.1	MH28-1-0.1	J1, J2	CONN HEADER VERT .100 1ROW 28POS 10.5 TAIL 8.5 BODY 15AU	
17	1	BLM31PG601SN1L	MURATA	BLM31PG601SN1L	FB1206	L1	FERRITE CHIP 600 OHM 1500MA 1206	
18	1	SWPA252012S1R0NT	SUNLORD	SWPA252012SMT	SWPA252012S	L2	INDUCTOR 1.2UH 2.0A SMD2.5 X 2.0 X 1.2	
19	1	DOMINO	GL-CONNECT	DOMINO-CORE	DOMINO	M1	MOD AR9331 WIFI	
20	2	10k	ANY	R0402_10k_5%_62.5mW	R0402	R1, R13	RES 10K OHM 1/16W 5% 0402 SMD	
21	1	270R	ANY	R0603_270R_5%_125mW	R0603	R10	RES 270 OHM 1/8W 5% 0603 SMD	
22	1	1k	ANY	R0402_1k_5%_62.5mW	R0402	R14	RES 1K OHM 1/16W 5% 0402 SMD	
23	1	33k2	ANY	R0402_33k2_1%_62.5mW	R0402	R2	RES 33.2K OHM 1/16W 1% 0402 SMD	
24	1	150k	ANY	R0402_150k_1%_62.5mW	R0402	R3	RES 150K OHM 1/16W 1% 0402 SMD	
25	1	47k	ANY	R0402_47k_5%_62.5mW	R0402	R4, R5(DNP)	RES 47K OHM 1/16W 5% 0402 SMD	
26	4	0R	ANY	R0402_0R_5%_62.5mW	R0402	R6, R7, R11, R12	RES 0.0 OHM 1/16W JUMP 0402 SMD	
27	1	270R	ANY	R0402_270R_5%_62.5mW	R0402	R8	RES 270 OHM 1/16W 5% 0402 SMD	
28	1	0R	ANY	R0603_0R_5%_125mW	R0603	R9	RES 0.0 OHM 1/8W JUMP SMD 0603	
29	1	USB_MR5-001	SZJUSTWELL ELECTRONICS	USB_MR5-001	USB_MR5-001	S1	CONN USB MICRO B RECPT SMT R/A	
30	1	IT-1210	SZJUSTWELL ELECTRONICS	IT-1210	IT-1210	SW1	SWITCH TACTILE SPST-NO 0.05A 12V	
31	1	MP2162GQH	MONOLITHIC POWER	MP2162GQH	QFN-8_2X1.5	U1	IC REG BUCK SYNC ADJ 2A 8WDFN	
32	1	CP2104-F03-GM	SILICON LABORATORIES	CP2104-F03-GM	QFN-25_4X4	U2	IC SGL USB-TO-UART BRIDGE 24QFN	
33	1	74LVC1G125DCK	TEXAS INSTRUMENTS	74LVC1G125DCK	SC70	U3	IC BUFF/DVR TRI-ST N-INV SC705	